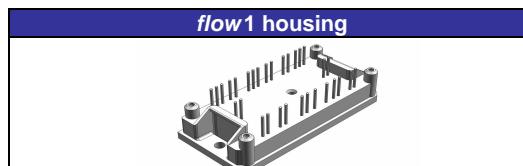
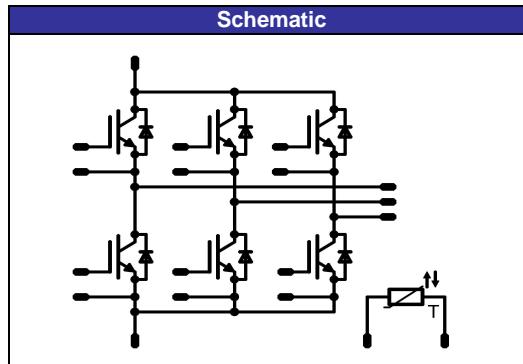


flowPACK 1 3rd gen**1200 V / 35 A**

Features
<ul style="list-style-type: none"> • Compact flow1 housing • Trench Fieldstop IGBT4 Technology • Compact and Low Inductance Design • Built-in NTC



Target Applications
<ul style="list-style-type: none"> • Motor Drive • Power Generation • UPS



Types
• V23990-P828-F10-PM

Maximum Ratings $T_j=25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
-----------	--------	-----------	-------	------

Inverter Transistor

Collector-emitter break down voltage	V_{CE}		1200	V
DC collector current	I_C	$T_j=T_{j\max}$	33	A
Repetitive peak collector current	I_{Cpulse}	t_p limited by $T_{j\max}$	105	A
Power dissipation	P_{tot}	$T_j=T_{j\max}$	81	W
Gate-emitter peak voltage	V_{GE}		± 20	V
Short circuit ratings	t_{sc} V_{CC}	$T_j \leq 150^\circ\text{C}$ $V_{GE}=15\text{V}$	10 800	μs V
Maximum Junction Temperature	$T_{j\max}$		175	$^\circ\text{C}$

Inverter Diode

Peak Repetitive Reverse Voltage	V_{RRM}	$T_j=25^\circ\text{C}$	1200	V
DC forward current	I_F	$T_j=T_{j\max}$	35	A
Repetitive peak forward current	I_{FRM}	t_p limited by $T_{j\max}$	70	A
Power dissipation	P_{tot}	$T_j=T_{j\max}$	63	W
Maximum Junction Temperature	$T_{j\max}$		175	$^\circ\text{C}$

Thermal Properties

Storage temperature	T_{stg}		-40...+125	$^\circ\text{C}$
Operation temperature under switching condition	T_{op}		-40...+150	$^\circ\text{C}$

Maximum Ratings

T_j=25°C, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
-----------	--------	-----------	-------	------

Insulation Properties

Insulation voltage	V _{is}	t=1min	4000	V _{DC}
Creepage distance			min 12,7	mm
Clearance			min 12,7	mm

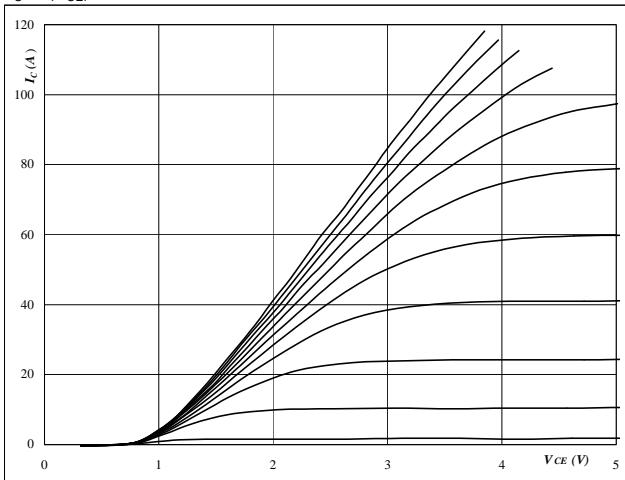
Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] or V_{GS} [V]	V_r [V] or V_{CE} [V] or V_{DS} [V]	I_c [A] or I_F [A] or I_D [A]	T_j	Min	Typ	Max	
Inverter Transistor										
Gate emitter threshold voltage	$V_{GE(th)}$	$V_{CE}=V_{GE}$			0,0012	$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$	5	5,8	6,5	V
Collector-emitter saturation voltage	$V_{CE(sat)}$		15		35	$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$	1,3	1,92 2,39	2,3	V
Collector-emitter cut-off current incl. Diode	I_{CES}		0	1200		$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$			0,015	mA
Gate-emitter leakage current	I_{GES}		20	0		$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$			200	nA
Integrated Gate resistor	R_{gint}							none		Ω
Turn-on delay time	$t_{d(on)}$	$R_{goff}=16 \Omega$ $R_{gon}=16 \Omega$	± 15	600	35	$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$		91 94		ns
Rise time	t_r					$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$		19 23		
Turn-off delay time	$t_{d(off)}$					$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$		204 264		
Fall time	t_f					$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$		72 109		
Turn-on energy loss per pulse	E_{on}					$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$		2,02 3,09		mWs
Turn-off energy loss per pulse	E_{off}					$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$		1,76 2,81		
Input capacitance	C_{ies}					$T_j=25^\circ\text{C}$		1950		pF
Output capacitance	C_{oss}	$f=1\text{MHz}$	0	25		$T_j=25^\circ\text{C}$		155		
Reverse transfer capacitance	C_{rss}							115		
Gate charge	Q_{Gate}	$V_{CC}=960\text{V}$	± 15		35	$T_j=25^\circ\text{C}$		180		nC
Thermal resistance chip to heatsink	R_{thJH}	Thermal grease thickness≤50μm $\lambda = 1 \text{ W/mK}$						1,18		K/W
Inverter Diode										
Diode forward voltage	V_F				35	$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$	1,35 1,77	1,80 2,35		V
Peak reverse recovery current	I_{RRM}	$R_{gon}=16 \Omega$	± 15	600	35	$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$		48 53		A
Reverse recovery time	t_{rr}					$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$		251 353		ns
Reverse recovered charge	Q_{rr}					$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$		3,56 6,93		nC
Peak rate of fall of recovery current	$d(i_{rec})/\text{max dt}$					$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$		2000 390		A/μs
Reverse recovered energy	E_{rec}					$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$		1,38 2,83		mWs
Thermal resistance chip to heatsink	R_{thJH}	Thermal grease thickness≤50μm $\lambda = 1 \text{ W/mK}$						1,52		K/W
Thermistor										
Rated resistance	R					$T_j=25^\circ\text{C}$		4,7		$\text{k}\Omega$
Deviation of R100	$\Delta R/R$	$R_{100}=401 \Omega$				$T_j=100^\circ\text{C}$	-12,4		12,4	%
Power dissipation	P					$T_j=25^\circ\text{C}$		210		mW
Power dissipation constant						$T_j=25^\circ\text{C}$		3,5		mW/K
B-value	$B(25/50)$					$T_j=25^\circ\text{C}$		3590		K
B-value	$B(25/100)$					$T_j=25^\circ\text{C}$		3650		K
Vincotech NTC Reference								D		

Output Inverter

Figure 1**Typical output characteristics**

$$I_C = f(V_{CE})$$

**At**

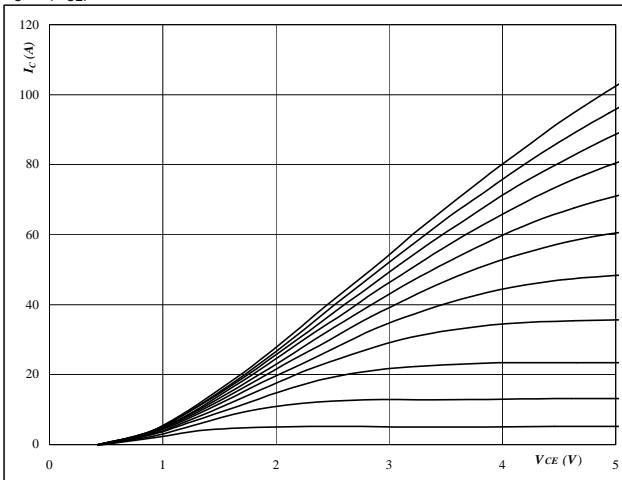
$$t_p = 250 \mu\text{s}$$

$$T_j = 25^\circ\text{C}$$

VGE from 7 V to 17 V in steps of 1 V

Output inverter IGBT**Figure 2****Typical output characteristics**

$$I_C = f(V_{CE})$$

**At**

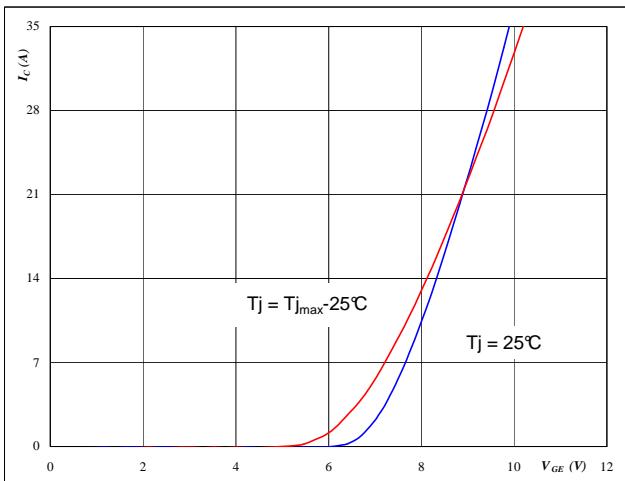
$$t_p = 250 \mu\text{s}$$

$$T_j = 150^\circ\text{C}$$

VGE from 7 V to 17 V in steps of 1 V

Figure 3**Typical transfer characteristics**

$$I_C = f(V_{GE})$$

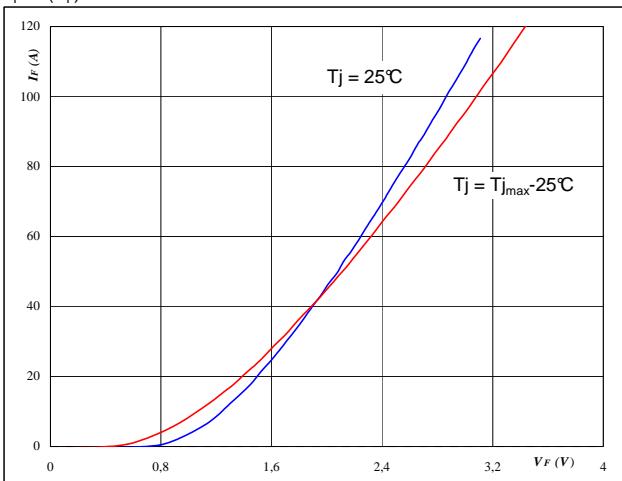
**At**

$$t_p = 250 \mu\text{s}$$

$$V_{CE} = 10 \text{ V}$$

Output inverter IGBT**Figure 4****Typical diode forward current as a function of forward voltage**

$$I_F = f(V_F)$$

**At**

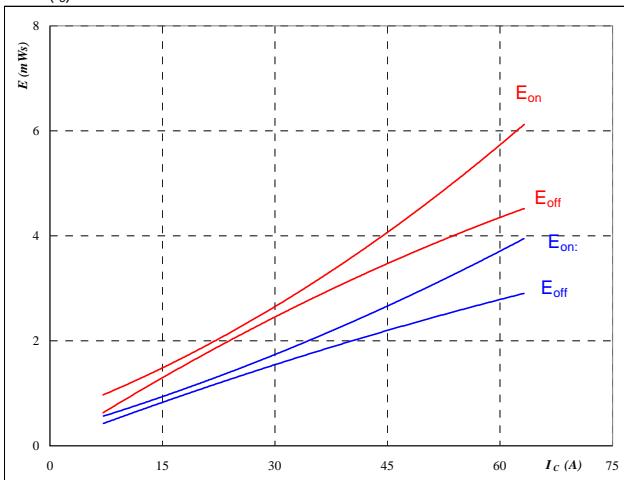
$$t_p = 250 \mu\text{s}$$

Output Inverter

Figure 5

**Typical switching energy losses
as a function of collector current**

$$E = f(I_C)$$



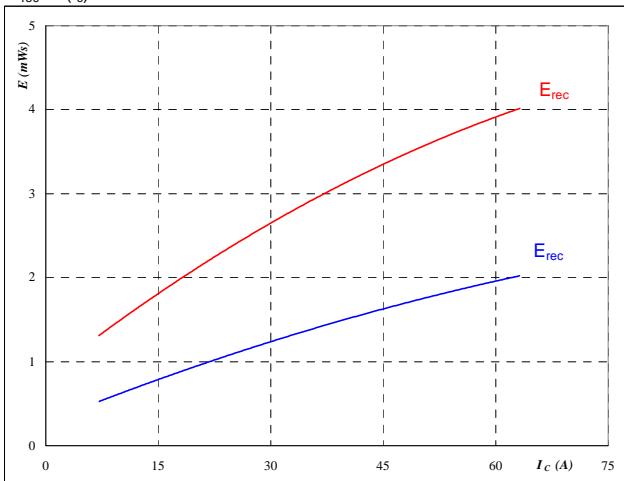
With an inductive load at

$$\begin{aligned} T_j &= 25/150 \quad ^\circ\text{C} \\ V_{CE} &= 600 \quad \text{V} \\ V_{GE} &= \pm 15 \quad \text{V} \\ R_{gon} &= 16 \quad \Omega \\ R_{goff} &= 16 \quad \Omega \end{aligned}$$

Figure 7

**Typical reverse recovery energy loss
as a function of collector current**

$$E_{rec} = f(I_C)$$



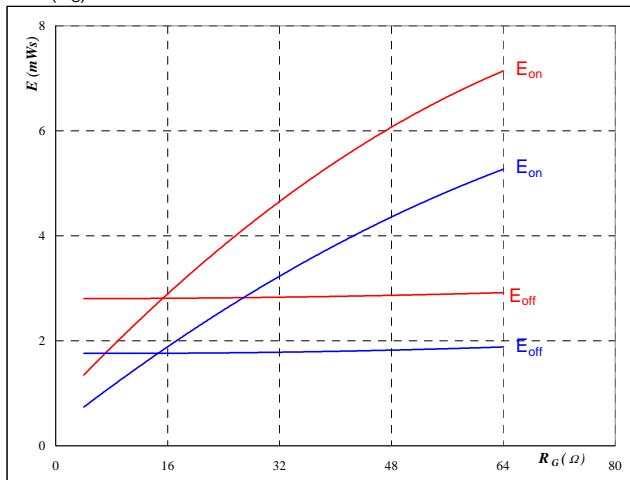
With an inductive load at

$$\begin{aligned} T_j &= 25/150 \quad ^\circ\text{C} \\ V_{CE} &= 600 \quad \text{V} \\ V_{GE} &= \pm 15 \quad \text{V} \\ R_{gon} &= 16 \quad \Omega \end{aligned}$$

Figure 6

**Typical switching energy losses
as a function of gate resistor**

$$E = f(R_G)$$



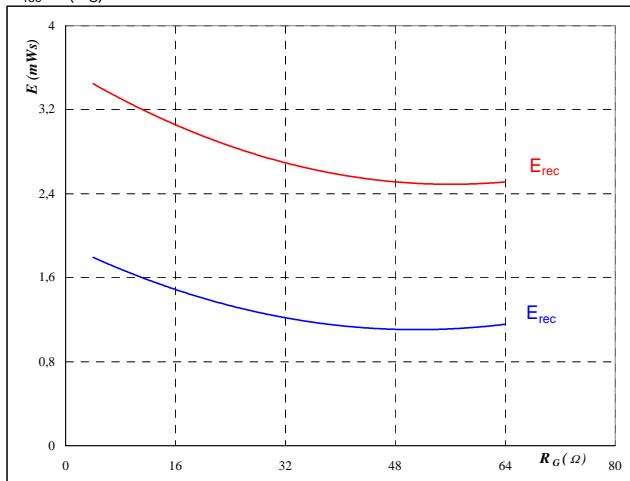
With an inductive load at

$$\begin{aligned} T_j &= 25/150 \quad ^\circ\text{C} \\ V_{CE} &= 600 \quad \text{V} \\ V_{GE} &= \pm 15 \quad \text{V} \\ I_C &= 35 \quad \text{A} \end{aligned}$$

Figure 8

**Typical reverse recovery energy loss
as a function of gate resistor**

$$E_{rec} = f(R_G)$$



With an inductive load at

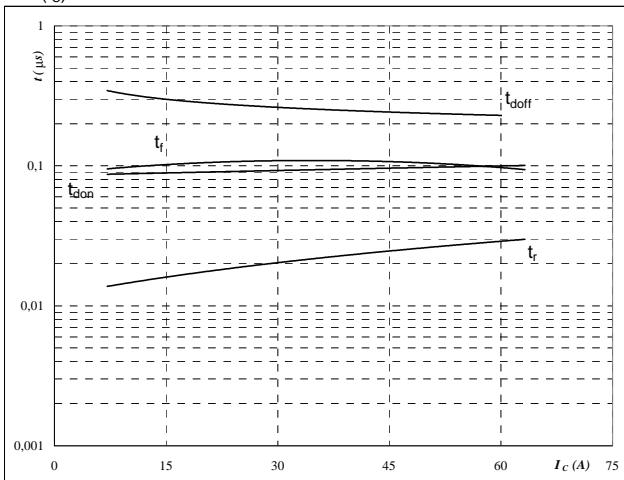
$$\begin{aligned} T_j &= 25/150 \quad ^\circ\text{C} \\ V_{CE} &= 600 \quad \text{V} \\ V_{GE} &= \pm 15 \quad \text{V} \\ I_C &= 35 \quad \text{A} \end{aligned}$$

Output Inverter

Figure 9

Typical switching times as a function of collector current

$$t = f(I_C)$$



With an inductive load at

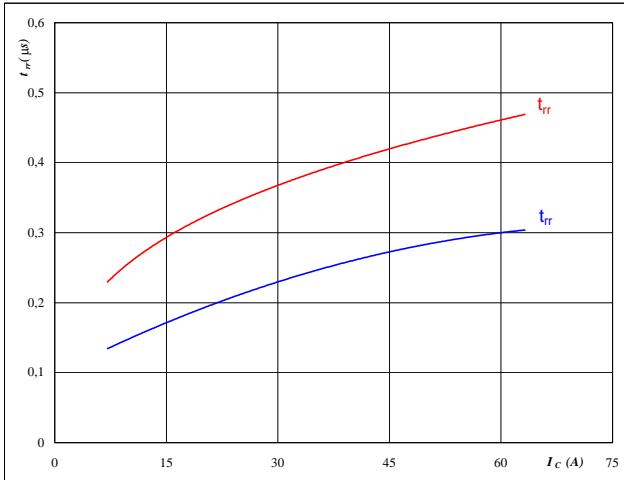
$T_j =$	150	°C
$V_{CE} =$	600	V
$V_{GE} =$	± 15	V
$R_{gon} =$	16	Ω
$R_{goff} =$	16	Ω

Figure 11

Output inverter FWD

Typical reverse recovery time as a function of collector current

$$t_{rr} = f(I_C)$$



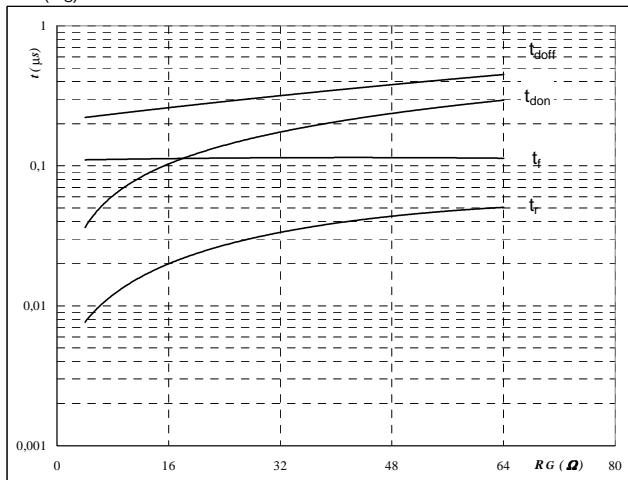
At

$T_j =$	25/150	°C
$V_{CE} =$	600	V
$V_{GE} =$	± 15	V
$R_{gon} =$	16	Ω

Figure 10

Typical switching times as a function of gate resistor

$$t = f(R_G)$$



With an inductive load at

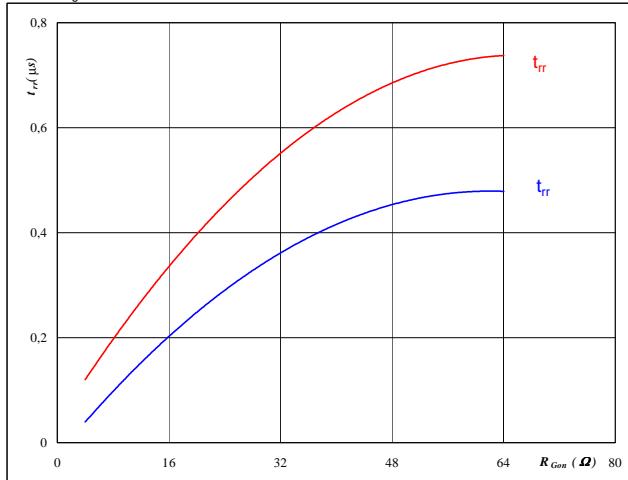
$T_j =$	150	°C
$V_{CE} =$	600	V
$V_{GE} =$	± 15	V
$I_C =$	35	A

Figure 12

Output inverter FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor

$$t_{rr} = f(R_{gon})$$



At

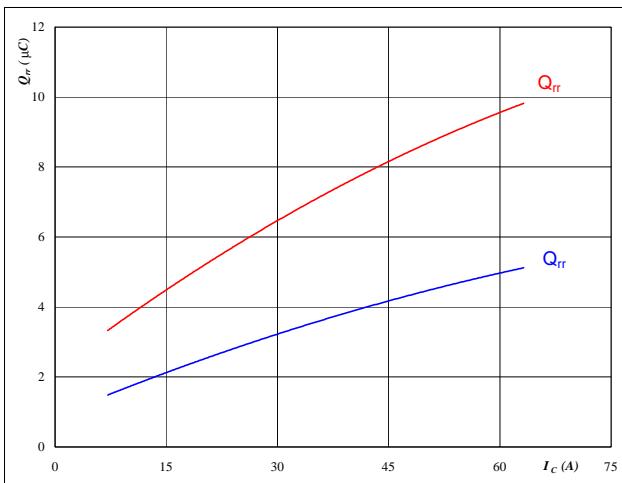
$T_j =$	25/150	°C
$V_R =$	600	V
$I_F =$	35	A
$V_{GE} =$	± 15	V

Output Inverter

Figure 13

Typical reverse recovery charge as a function of collector current

$$Q_{rr} = f(I_c)$$

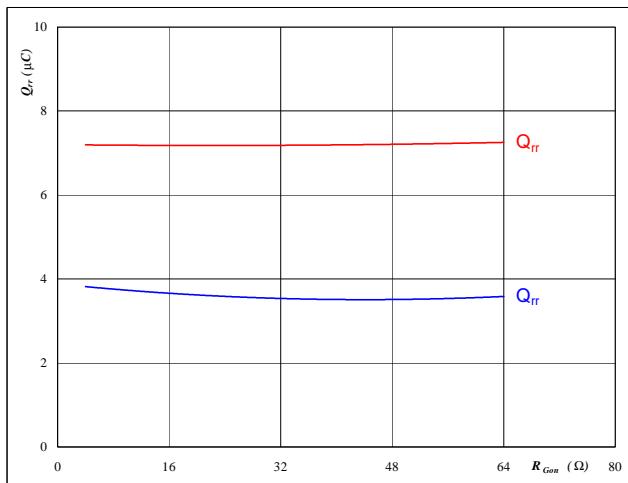
**At**

$$\begin{aligned} T_j &= 25/150 \quad ^\circ\text{C} \\ V_{CE} &= 600 \quad \text{V} \\ V_{GE} &= \pm 15 \quad \text{V} \\ R_{Gon} &= 16 \quad \Omega \end{aligned}$$

Output inverter FWD
Figure 14

Typical reverse recovery charge as a function of IGBT turn on gate resistor

$$Q_{rr} = f(R_{gon})$$

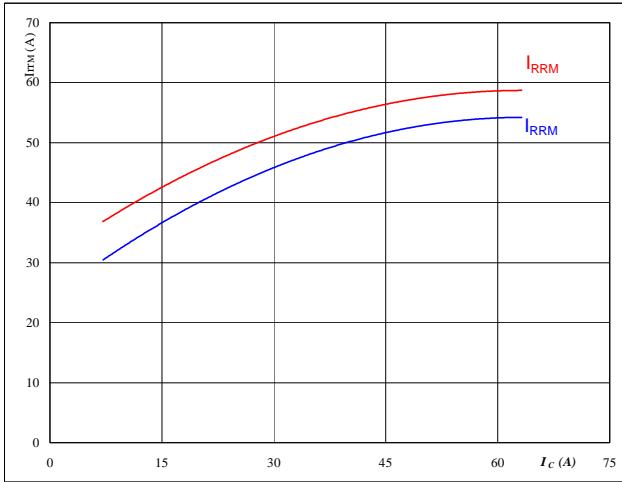
**At**

$$\begin{aligned} T_j &= 25/150 \quad ^\circ\text{C} \\ V_R &= 600 \quad \text{V} \\ I_F &= 35 \quad \text{A} \\ V_{GE} &= \pm 15 \quad \text{V} \end{aligned}$$

Figure 15
Output inverter FWD

Typical reverse recovery current as a function of collector current

$$I_{RRM} = f(I_c)$$

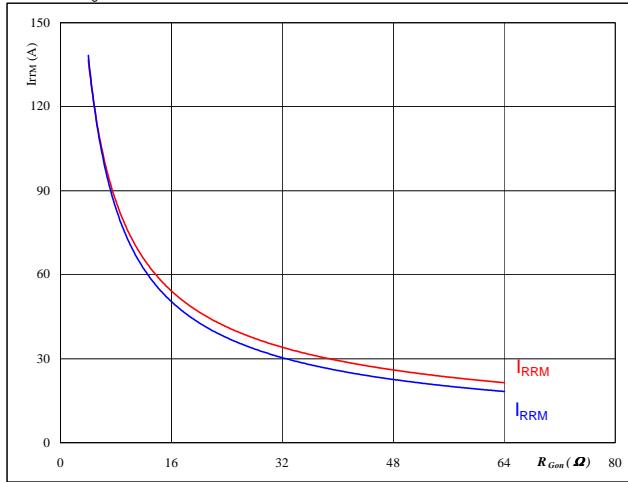
**At**

$$\begin{aligned} T_j &= 25/150 \quad ^\circ\text{C} \\ V_{CE} &= 600 \quad \text{V} \\ V_{GE} &= \pm 15 \quad \text{V} \\ R_{Gon} &= 16 \quad \Omega \end{aligned}$$

Figure 16
Output inverter FWD

Typical reverse recovery current as a function of IGBT turn on gate resistor

$$I_{RRM} = f(R_{gon})$$

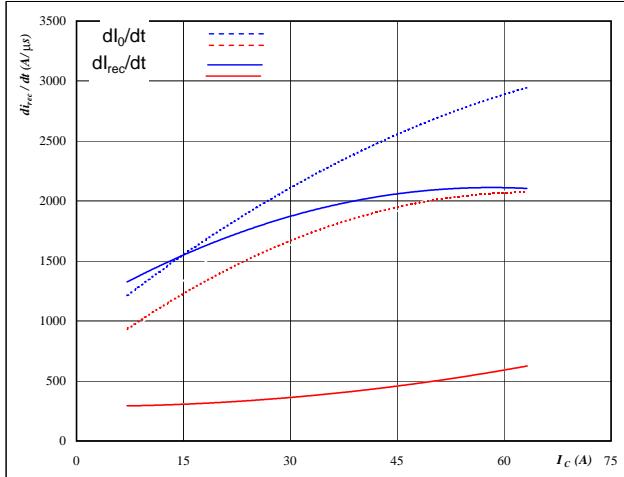
**At**

$$\begin{aligned} T_j &= 25/150 \quad ^\circ\text{C} \\ V_R &= 600 \quad \text{V} \\ I_F &= 35 \quad \text{A} \\ V_{GE} &= \pm 15 \quad \text{V} \end{aligned}$$

Output Inverter

Figure 17

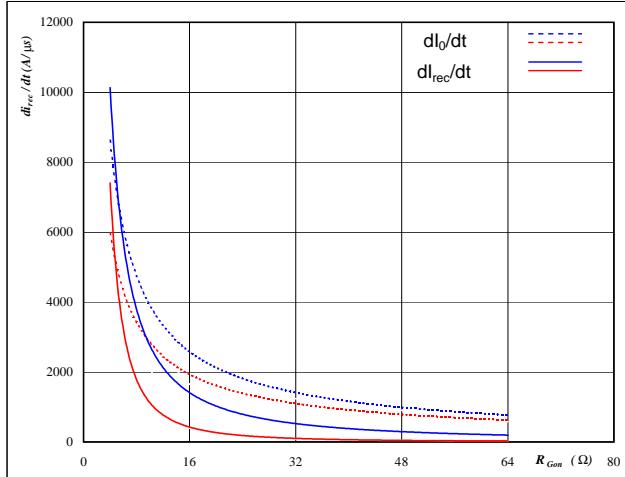
Typical rate of fall of forward
and reverse recovery current as a
function of collector current
 $dI_0/dt, dI_{rec}/dt = f(I_c)$


At

$T_j =$	25/150	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$R_{Gon} =$	16	Ω

Output inverter FWD
Figure 18

Typical rate of fall of forward
and reverse recovery current as a
function of IGBT turn on gate resistor
 $dI_0/dt, dI_{rec}/dt = f(R_{Gon})$

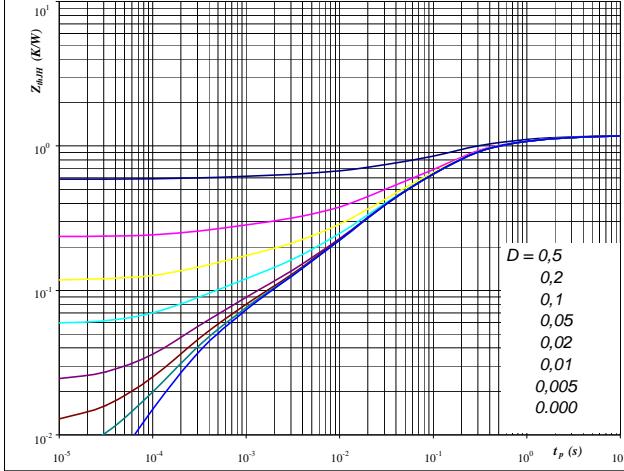

At

$T_j =$	25/150	°C
$V_R =$	600	V
$I_F =$	35	A
$V_{GE} =$	±15	V

Figure 19

IGBT transient thermal impedance
as a function of pulse width

$$Z_{thJH} = f(t_p)$$


At

$D =$	t_p / T
$R_{thJH} =$	1,18 K/W

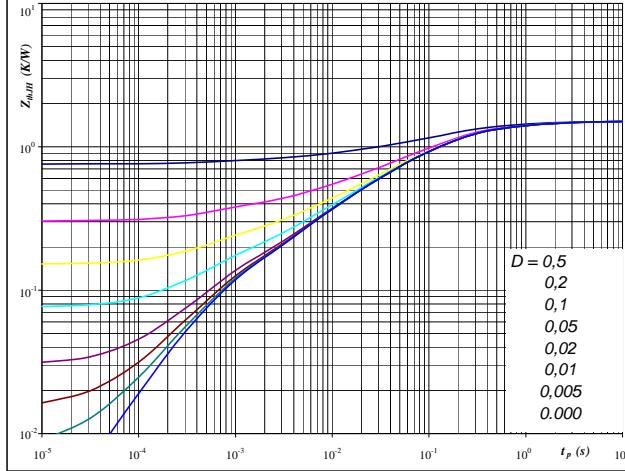
IGBT thermal model values

R (K/W)	Tau (s)
0,07	3,9E+00
0,25	5,9E-01
0,56	1,3E-01
0,21	1,8E-02
0,05	2,0E-03
0,04	3,1E-04

Output inverter IGBT
Figure 20

FWD transient thermal impedance
as a function of pulse width

$$Z_{thJH} = f(t_p)$$


At

$D =$	t_p / T
$R_{thJH} =$	1,52 K/W

FWD thermal model values

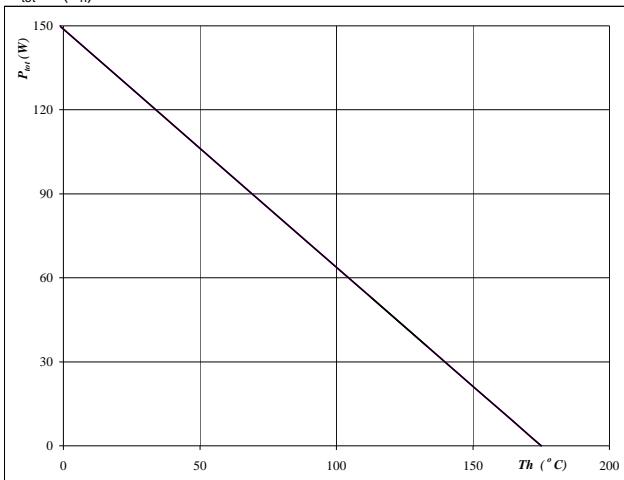
R (K/W)	Tau (s)
0,05	9,6E+00
0,19	1,0E+00
0,67	1,6E-01
0,34	3,4E-02
0,18	6,6E-03
0,10	6,1E-04

Output Inverter

Figure 21

Power dissipation as a function of heatsink temperature

$$P_{\text{tot}} = f(T_h)$$

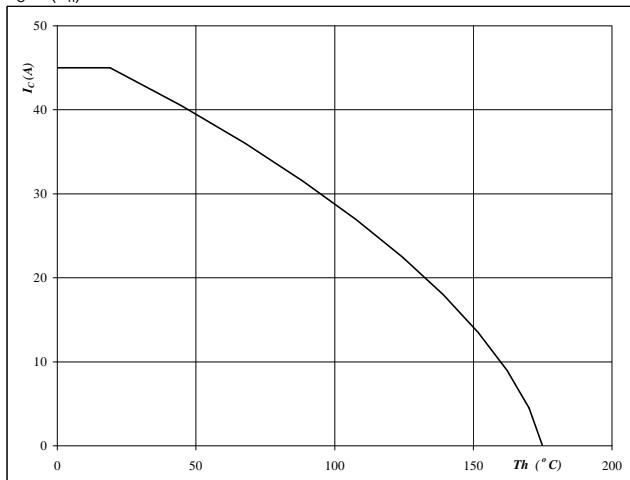
**At**

$$T_j = 175 \quad ^\circ\text{C}$$

Output inverter IGBT**Figure 22**

Collector current as a function of heatsink temperature

$$I_C = f(T_h)$$

**At**

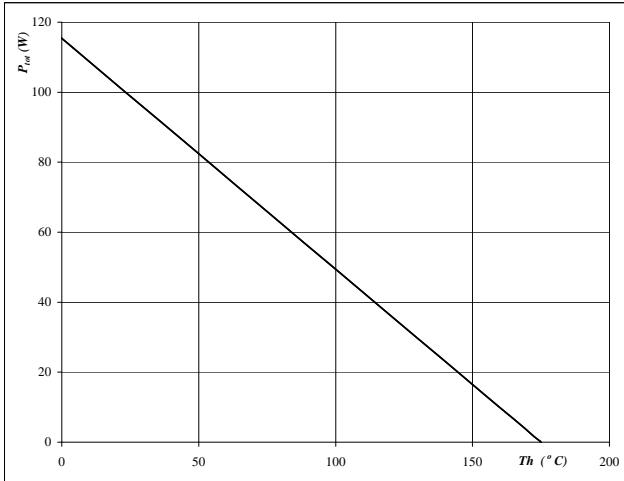
$$T_j = 175 \quad ^\circ\text{C}$$

$$V_{GE} = 15 \quad \text{V}$$

Figure 23**Output inverter FWD**

Power dissipation as a function of heatsink temperature

$$P_{\text{tot}} = f(T_h)$$

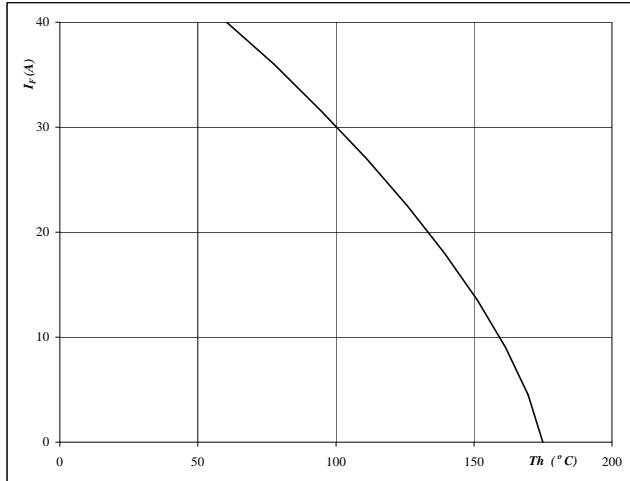
**At**

$$T_j = 175 \quad ^\circ\text{C}$$

Figure 24**Output inverter FWD**

Forward current as a function of heatsink temperature

$$I_F = f(T_h)$$

**At**

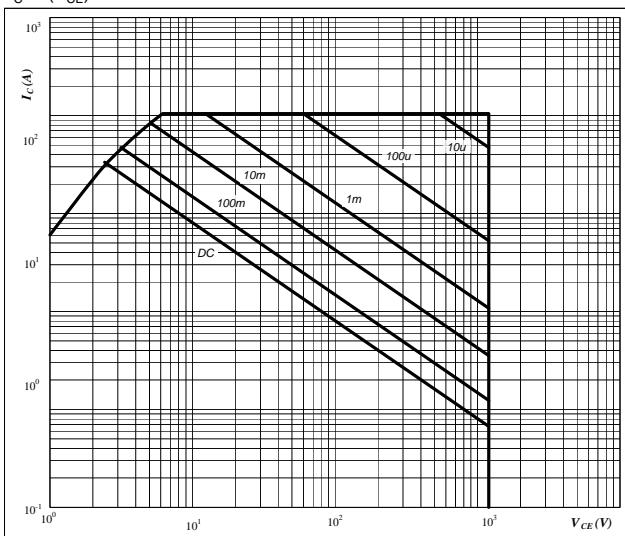
$$T_j = 175 \quad ^\circ\text{C}$$

Output Inverter

Figure 25

**Safe operating area as a function
of collector-emitter voltage**

$$I_C = f(V_{CE})$$

**At**

D = single pulse

Th = 80 °C

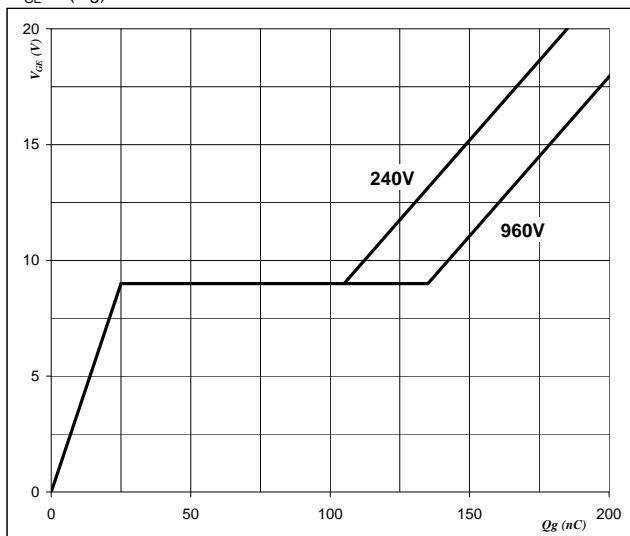
V_{GE} = ±15 V

T_j = T_{jmax} °C

Figure 26

Gate voltage vs Gate charge

$$V_{GE} = f(Qg)$$

**At**

I_C = 35 A

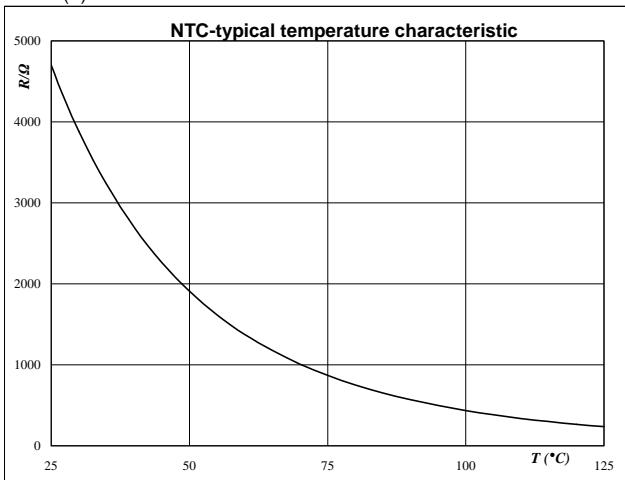
Thermistor

Figure 1

Thermistor

Typical NTC characteristic
as a function of temperature

$$R_T = f(T)$$



Switching Definitions Output Inverter

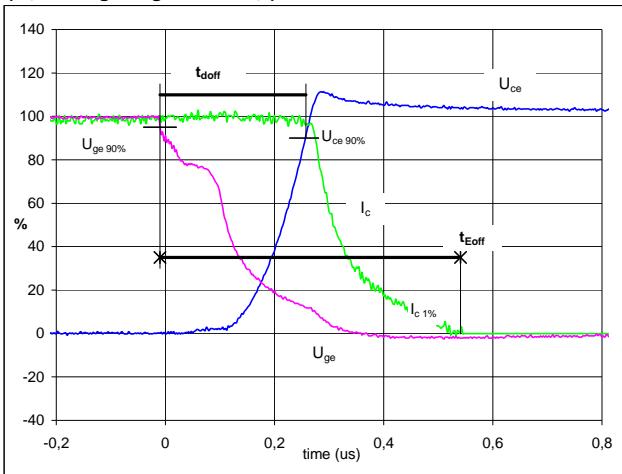
General conditions

T_j	= 150 °C
R_{gon}	= 16 Ω
R_{goff}	= 16 Ω

Figure 1

Output inverter IGBT

Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff}
 $(t_{Eoff} = \text{integrating time for } E_{off})$

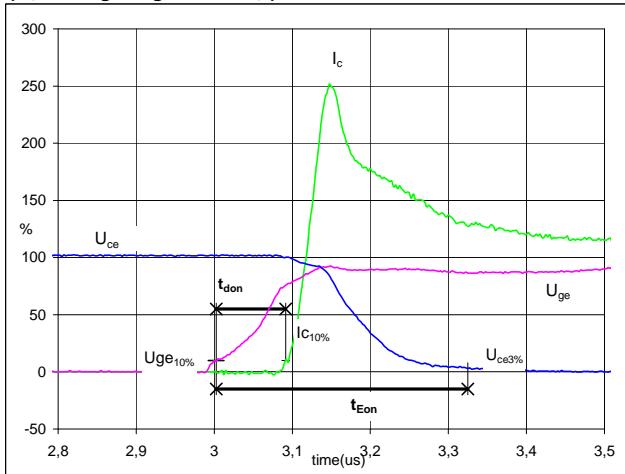


$V_{GE}(0\%) = -15$ V
 $V_{GE}(100\%) = 15$ V
 $V_C(100\%) = 600$ V
 $I_C(100\%) = 35$ A
 $t_{doff} = 0,26$ μs
 $t_{Eoff} = 0,55$ μs

Figure 2

Output inverter IGBT

Turn-on Switching Waveforms & definition of t_{don} , t_{Eon}
 $(t_{Eon} = \text{integrating time for } E_{on})$

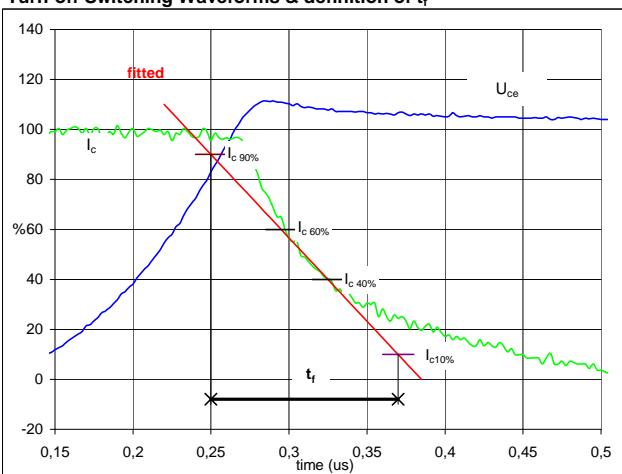


$V_{GE}(0\%) = -15$ V
 $V_{GE}(100\%) = 15$ V
 $V_C(100\%) = 600$ V
 $I_C(100\%) = 35$ A
 $t_{don} = 0,09$ μs
 $t_{Eon} = 0,32$ μs

Figure 3

Output inverter IGBT

Turn-off Switching Waveforms & definition of t_f

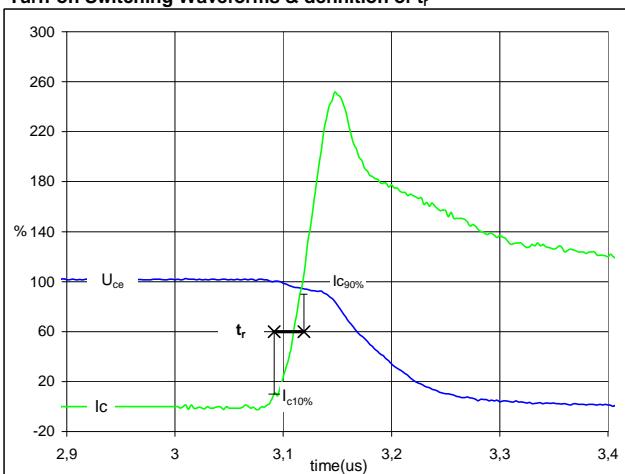


$V_C(100\%) = 600$ V
 $I_C(100\%) = 35$ A
 $t_f = 0,11$ μs

Figure 4

Output inverter IGBT

Turn-on Switching Waveforms & definition of t_r

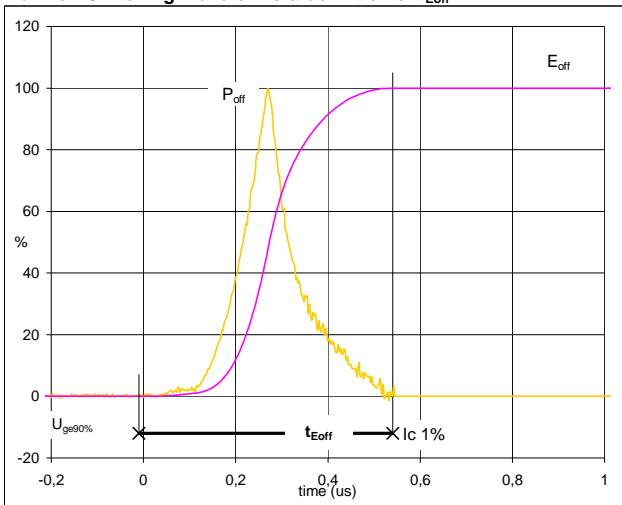


$V_C(100\%) = 600$ V
 $I_C(100\%) = 35$ A
 $t_r = 0,02$ μs

Switching Definitions Output Inverter

Figure 5

Output inverter IGBT

Turn-off Switching Waveforms & definition of t_{Eoff} 

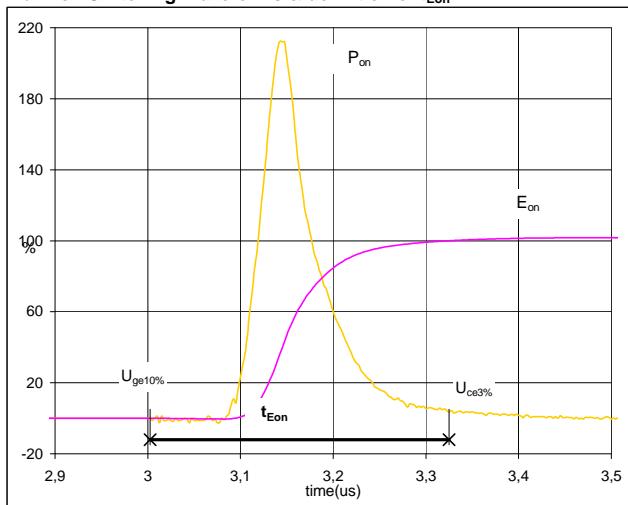
$P_{off} (100\%) = 20,98 \text{ kW}$

$E_{off} (100\%) = 2,81 \text{ mJ}$

$t_{Eoff} = 0,55 \mu\text{s}$

Figure 6

Output inverter IGBT

Turn-on Switching Waveforms & definition of t_{Eon} 

$P_{on} (100\%) = 20,98 \text{ kW}$

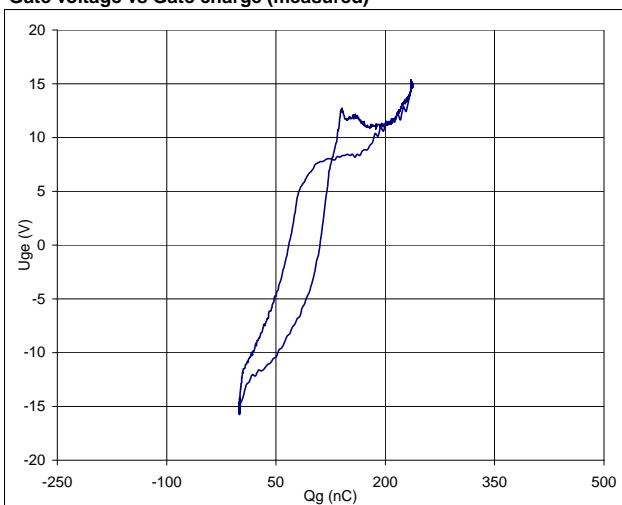
$E_{on} (100\%) = 3,09 \text{ mJ}$

$t_{Eon} = 0,32 \mu\text{s}$

Figure 7

Output inverter FWD

Gate voltage vs Gate charge (measured)



$V_{GEoff} = -15 \text{ V}$

$V_{GEon} = 15 \text{ V}$

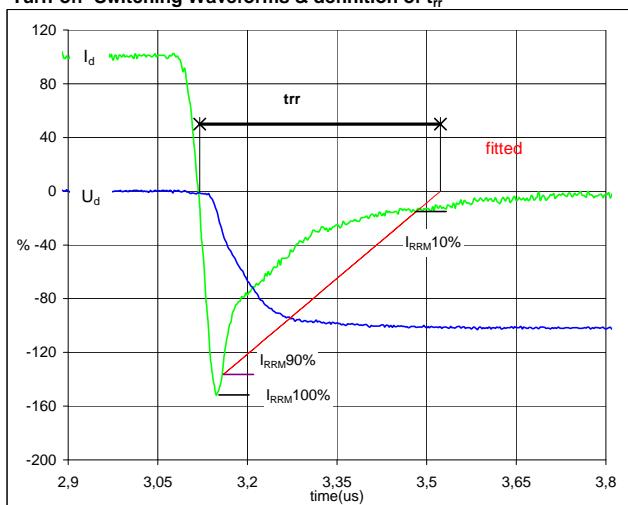
$V_C (100\%) = 600 \text{ V}$

$I_C (100\%) = 35 \text{ A}$

$Q_g = 236,86 \text{ nC}$

Figure 8

Output inverter IGBT

Turn-off Switching Waveforms & definition of t_{rr} 

$V_d (100\%) = 600 \text{ V}$

$I_d (100\%) = 35 \text{ A}$

$I_{RRM} (100\%) = -53 \text{ A}$

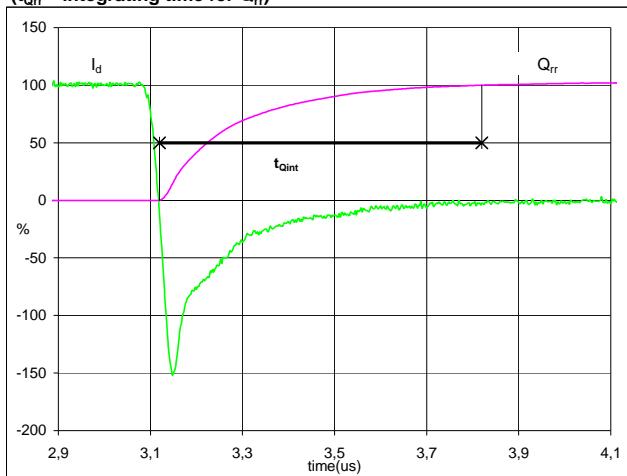
$t_{rr} = 0,35 \mu\text{s}$

Switching Definitions Output Inverter

Figure 9

Output inverter FWD

Turn-on Switching Waveforms & definition of t_{Qrr}
 $(t_{Qrr} = \text{integrating time for } Q_{rr})$

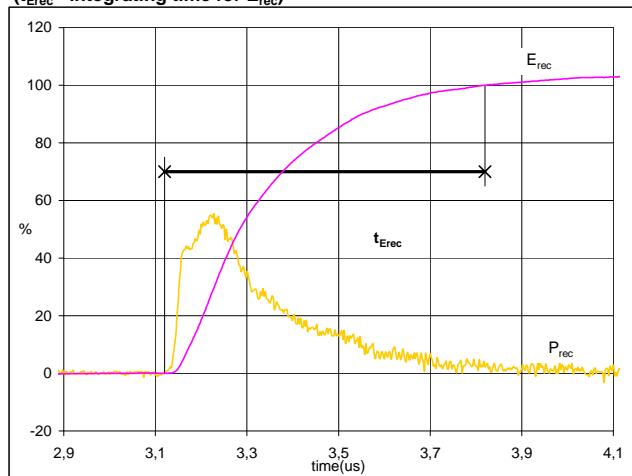


$I_d(100\%) = 35 \text{ A}$
 $Q_{rr}(100\%) = 6,93 \mu\text{C}$
 $t_{Qint} = 0,70 \mu\text{s}$

Figure 10

Output inverter FWD

Turn-on Switching Waveforms & definition of t_{Erec}
 $(t_{Erec} = \text{integrating time for } E_{rec})$



$P_{rec}(100\%) = 20,98 \text{ kW}$
 $E_{rec}(100\%) = 2,83 \text{ mJ}$
 $t_{Erec} = 0,70 \mu\text{s}$

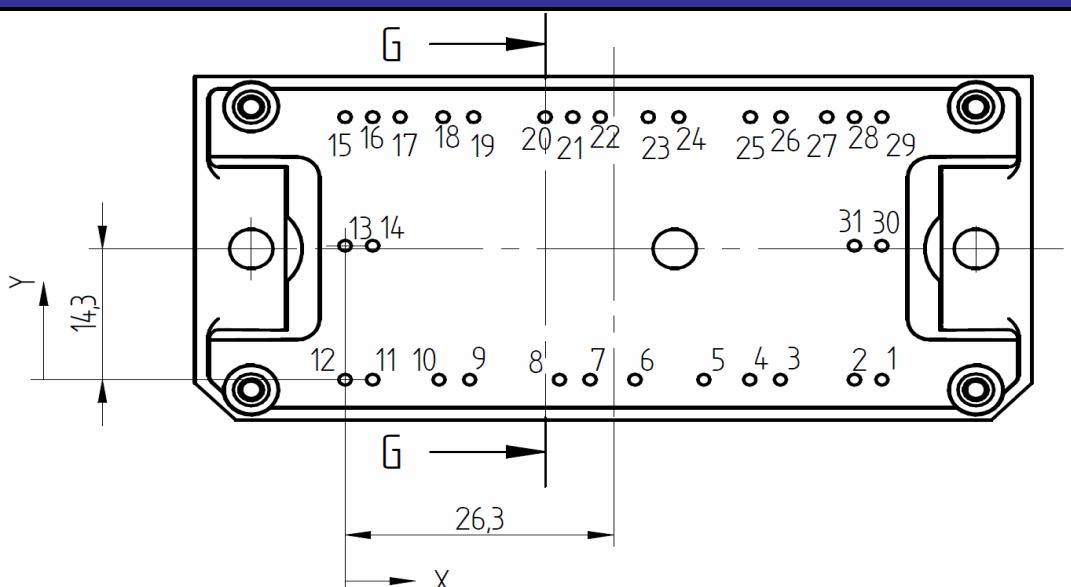
Ordering Code and Marking - Outline - Pinout

Ordering Code & Marking

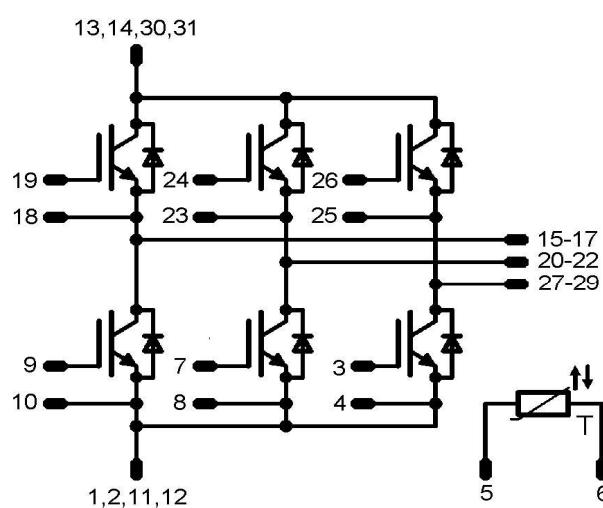
Version	Ordering Code	in DataMatrix as	in packaging barcode as
without thermal paste 17mm housing	V23990-P828-F10-PM	P828-F10	P828-F10

Outline

Pin table		
Pin	X	Y
1	52,6	0
2	49,9	0
3	42,65	0
4	39,65	0
5	35,15	2,8
6	28,4	0
7	24	2,8
8	21	0
9	12,2	0
10	9,2	0
11	2,7	0
12	0	0
13	0	14,65
14	2,7	14,65
15	0	28,6
16	2,7	28,6
17	5,4	28,6
18	9,6	28,6
19	12,6	28,6
20	19,6	28,6
21	22,3	28,6
22	25	28,6
23	29,7	28,6
24	32,7	28,6
25	39,7	28,6
26	42,7	28,6
27	42,2	28,6
28	49,9	28,6
29	52,6	28,6
30	52,6	14,56
31	49,9	14,56



Pinout



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